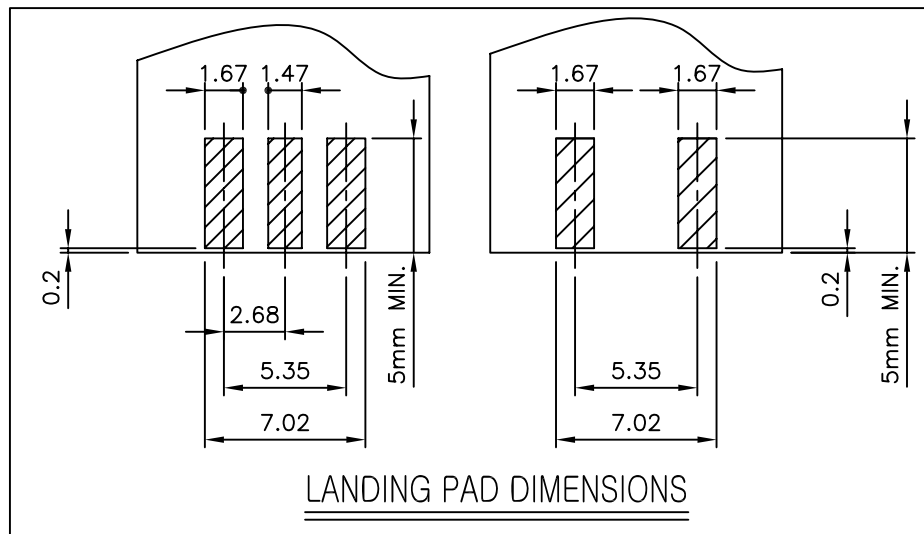
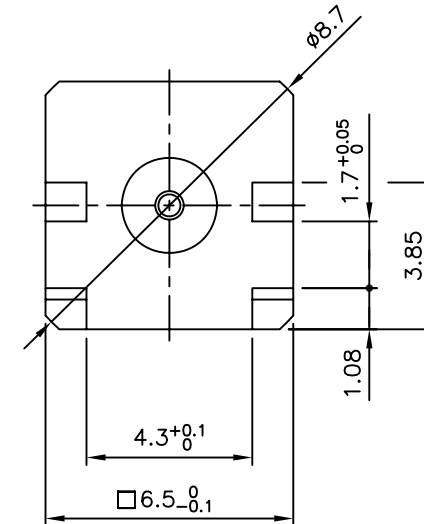
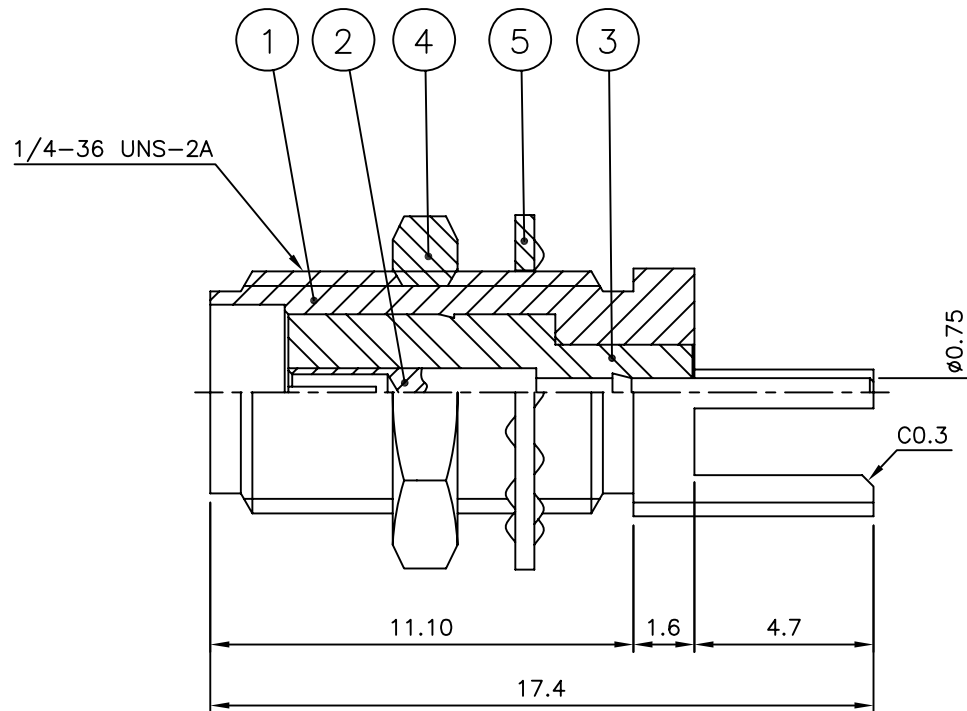
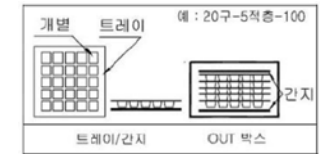


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	I.C.KIM	J.H.YOUN	2012.04.11.

■포장사양

- 부광하이텍 327-3호 (PET) 50구 Tray 사용
- Tray 개당 제품 2ea씩 포장 (Total 100ea)
- NUT/WASHER V-100-B 별도포장



LANDING PAD DIMENSIONS

5	WASHER	1	BsS	Gold Plate	DWA00005-5/1
4	NUT	1	MBsBD	Gold Plate	DNT00025-5/1
3	INSULATOR	1	TEFLON		DIN02001-N/1
2	CONTACT	1	BeCu	Gold Plate	DCT02584-5/1
1	BODY	1	MBsBD	Gold Plate	DBD03045-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2012. 04. 11.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	J.H.YOUN	
MATERIAL		CHECKED BY		KJ COMTECH CO.,LTD. TITLE SMA50 PCB JS-4R Edge
		DRAWN BY	I.C.KIM	
FINISH		SCALE	5/1	A4 DWG NO. CN02791-7/1 REVISION I R SHEET 1 of 1
		UNIT	mm	